



Statement of Materials, Construction

LEAD-FREE -- 14L-SOICN -- TABLE OF MATERIAL DECLARATION								
No.	Component Name	Material Name	Component Weight (grams)	Materials Analysis (Element/Compound)	CAS Number	Material Mass (grams)	Material Weight % (of Total Pkg.)	Material Weight % (of Component)
1	Leadframe	Copper Alloy	0.04914	Cu	7440-50-8	0.04777	34.56463	97.21
				Fe	7439-89-6	0.00115	0.83556	2.35
				Pb	7439-92-1	0.00001	0.01067	0.03
				P	7723-14-0	0.00004	0.02933	0.08
				Silver (plating)	7440-22-4	0.00010	0.07111	0.20
				Zn	7440-66-6	0.00006	0.04444	0.13
2	Die	Silicon Chip	0.00362	Si	7440-21-3	0.00360	2.60617	99.50
3	Die Attach Material	Conductive Epoxy	0.00110	Epoxy Resin	Proprietary	0.00017	0.11939	15.00
				Silver	7440-22-4	0.00087	0.63275	79.50
				Aromatic Amine	Proprietary	0.00006	0.04377	5.50
4	Wire	Gold	0.00049	Au	7440-57-5	0.00049	0.35451	99.99
5	Lead Finish	Tin	0.00230	Sn	7440-31-5	0.00230	1.66417	100.00
6	Encapsulation	Epoxy Resin	0.08156	Fused Silica	60676-86-0	0.06541	47.32647	80.20
				Epoxy Resin	Proprietary	0.00816	5.90106	10.00
				Phenol Resin	9003-35-4	0.00408	2.95053	5.00
				Carbon Black	1333-86-4	0.00024	0.17703	0.30
				Brominated Epoxy Resin	68541-56-0	0.00204	1.47526	2.50
				Antimony Trioxide	1309-64-4	0.00163	1.04916	2.00
Total Package Weight			0.13821					

Note: Component Weight based on assembly of generic parts.

Conclusion:

The analysis table above shows that this package meets the following RoHS requirements for EACH PACKAGE COMPONENT (mold compound, lead frame, etc.)

	Maximum Allowable Limit (ppm)	Maximum Allowable Limit (wt %)
Lead	1000 ppm	0.10%
Mercury	1000 ppm	0.10%
Cadmium	100 ppm	0.01%
Hexavalent Chromium	1000 ppm	0.10%
Polybrominated Biphenyls (PBB)	1000 ppm	0.10%
Polybrominated Biphenylethers (PBDE)	1000 ppm	0.10%